

PCN Number: 20160615001 **PCN Date:** 06/21/2016

Title: Qualification of RFAB for Select LBC8 Devices

Customer Contact: [PCN Manager](#) **Dept:** Quality Services

Proposed 1st Ship Date: 09/21/2016 **Estimated Sample Availability:** Date provided at sample request.

Change Type:		
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>
<input type="checkbox"/>	Design	<input type="checkbox"/>
<input type="checkbox"/>	Test Site	<input type="checkbox"/>
<input checked="" type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>
<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>
<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>
<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>
<input type="checkbox"/>	Part number change	<input type="checkbox"/>

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional wafer Fab source for the selected devices listed in "Product Affected" section.

Current Sites				Additional Sites			
Current Fab Site	Fab Process	Bump Site	Wafer Diameter	Additional Fab Site	Fab Process	Bump Site	Wafer Diameter
DP1DM5	LBC8	DBUMP	200 mm	RFAB	LBC8	Clark-BP	300 mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current			
Chip Sites	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DP1DM5	DM5	USA	Dallas
New			
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
RFAB	RFB	USA	Richardson

Sample product shipping label (not actual product label)



MADE IN: Malaysia
2DC: 20:

MSL 2 / 260C / 1 YEAR	SEAL DT
MSL 1 / 235C / UNLIM	03/29/04

OPT: 39
ITEM: 39
LBL: 5A (L)T0:1750



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483S12
(P)
(2P) REV. (V) 0033317
(20L) CS0: SHE (21L) CC0: USA
(22L) AS0: MLA (23L) AC0: MYS

Product Affected:

DRV8711DCP

DRV8711DCPR

Qualification Report**LBC8 Offload from DM5 to RFAB; Gort (DRV8711DCP)
Approve Date 03-Jun-2016****Product Attributes**

Attributes	Qual Device: DRV8711DCP (GORT)	QBS Product Reference: DRV8711DCP	QBS Process Reference: SN96019PFP	QBS Package Reference: ALM2402QPWPRQ1	QBS Package Reference: TAS5548DCA
Assembly Site	TI TAIWAN	TAI / TITL	PHI (TIPI)	TAI (TITL)	TAI
Package Family	HTSSOP	HTSSOP	HTQFP	HTSSOP	HTSSOP
Wafer Fab Supplier	RFAB	DM0S5	RFAB	RFAB/DMOS6	RFAB
Wafer Fab Process	LBC8	LBC8	LBC8	LBC7	1833C05

- QBS: Qual by Similarity

- Qual Device DRV8711DCP (GORT) is qualified at LEVEL2-260C

Qualification Results**Data Displayed as: Number of lots / Total sample size / Total failed**

Type	Test Name / Condition	Duration	Qual Device: DRV8711DCP (GORT)	QBS Product Reference: DRV8711DCP	QBS Process Reference: SN96019PFP	QBS Package Reference: ALM2402QPWPRQ1	QBS Package Reference: TAS5548DCA
AC	Autoclave 121C	96 Hours	-	-	3/240/0	3/255/0	3/240/0
CDM	ESD CDM	+/- 1000V	1/3/0	-	-	-	-
ED	Auto Electrical Distributions	Cpk>1.67 Room, hot, and cold test	-	-	-	3/90/0	-
ED	Electrical Characterization	Per Datasheet Parameters	1/Pass	-	-	-	-
HAST	Biased HAST, 130C/85%RH	96 hours	-	-	3/240/0	3/253/0	-
HBM	ESD - HBM	2500 V	1/3/0	-	-	-	1/3/0
HTOL	Life Test, 125C	1000	-	-	3/239/0	-	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	3/240/0	-	3/240/0
LU	Latch-up	(per JESD78)	1/6/0	-	1/6/0	-	1/6/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	-	-	1/Pass	-	3/Pass
MQ	Manufacturability (Wafer Fab)	(per mfg. Site specification)	1/Pass	1/Pass	1/Pass	-	-
TC	Temperature Cycle, - 65/150C	500 Cycles	-	-	3/231/0	3/260/0	3/240/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>**Green/Pb-free Status:**

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com